

For fine pattern formation, high joint reliability

Electroless nickel/ gold plating process

- ▶ High fine patterning property, ideal for micro pattern plating
- ▶ Localized copper corrosion is suppressed, reduce voids
- ▶ Reduce pinholes, can obtain dense plating films
- ▶ Excellent in solder joint performance and solder wettability

Treatment process

Cleaning·etching·acid cleaning

Catalyzing

Sulfuric-acid based,
low Pd concentration (7mg/L)
ICP ACCERA KCS

Post-dipping

Low concentration, chelate-type,
Pd remover
ICP POSTDIP RP-S

Electroless Ni plating

High deposition performance
to small electrodes

(For FPC)

ICP NICORON FPF-TM

(For rigid boards)

ICP NICORON GM-EC

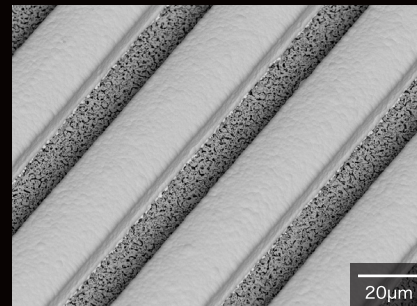
Electroless Au plating

High solder joint performance

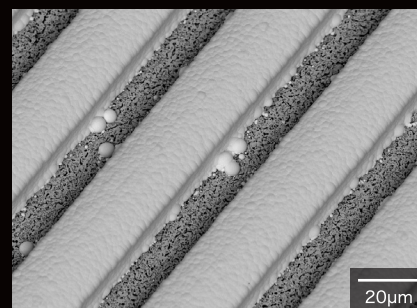
FLASH GOLD 330GS

Best for fine pattern formation

New
process



Conventional
process



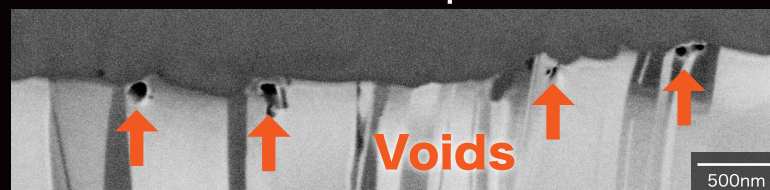
L/S=20/20μm
Surface SEM images after electroless Ni/Au plating
(Thickness:4.0μm/0.05μm)

Reduce voids on micro electrodes

New process



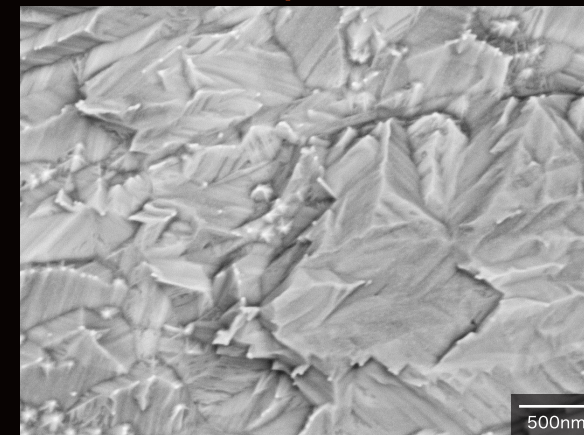
Conventional process



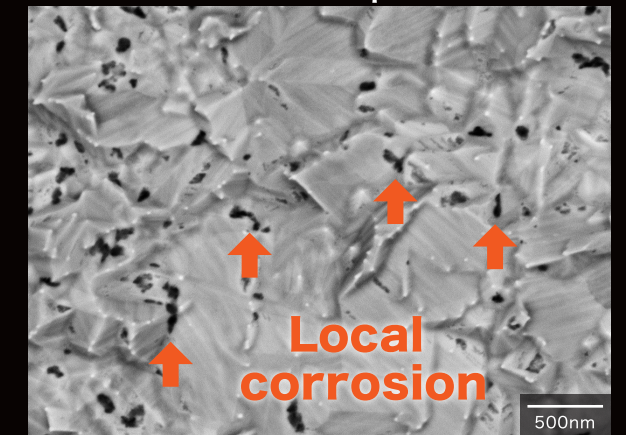
Cross-section SIM images after electroless Ni plating
at 60μm-diameter electrodes

Prevent copper corrosion

New process



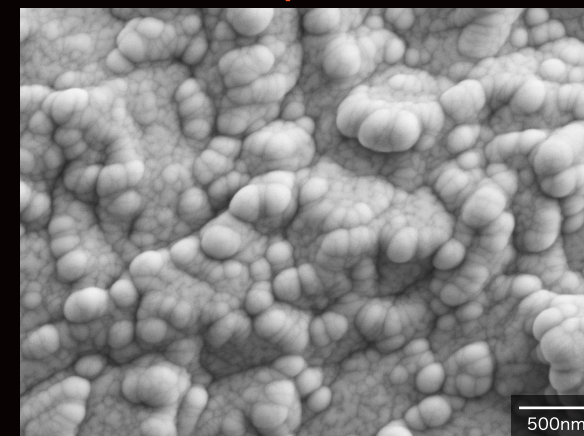
Conventional process



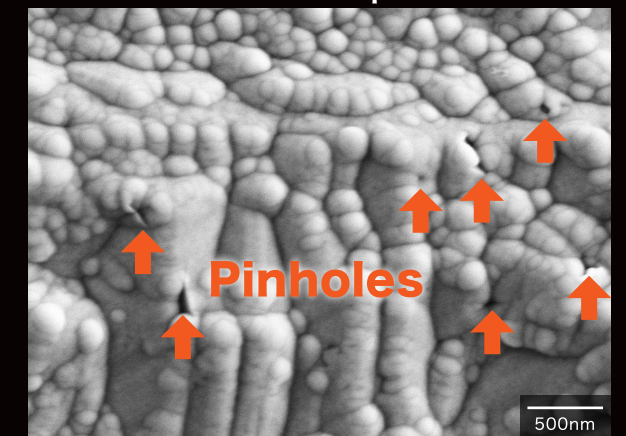
Surface backscattered image after catalyzing

Dense and fine nickel-plating film

New process



Conventional process



Surface SEM image after electroless Ni plating (Thickness:0.2μm)

High solder wettability, solder joint performance

